

GHB-1206L-B3

Features

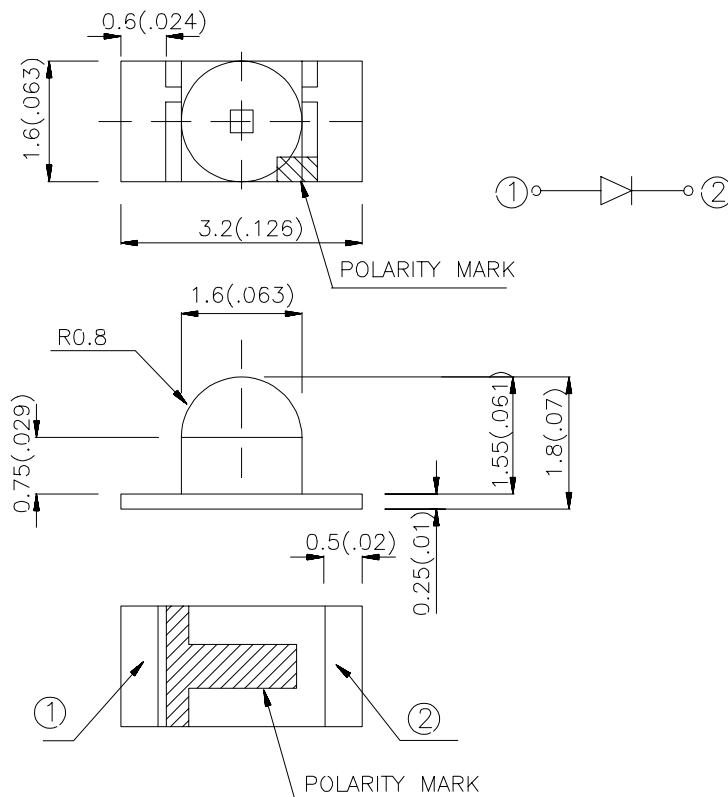
- ✓ 3.2mmx1.6mm SMT LED, 1.8mm THICKNESS.
- ✓ LOW POWER CONSUMPTION.
- ✓ WIDE VIEWING ANGLE.
- ✓ IDEAL FOR BACKLIGHT AND INDICATOR.
- ✓ PACKAGE : 2000PCS / REEL.

Description

The Blue source color devices are made with GaN on Sapphire Light Emitting Diode.

3.2x1.6mm SMD CHIP LED LAMP

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is 0.1(0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
GHB-1206L-B3	BLUE (GaN)	WATER CLEAR	180	350	40

Note:

- 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25 C

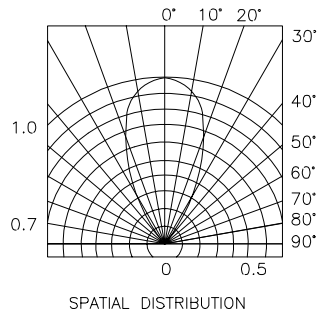
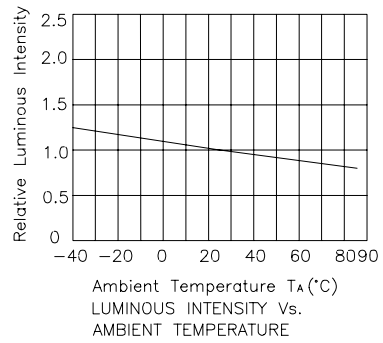
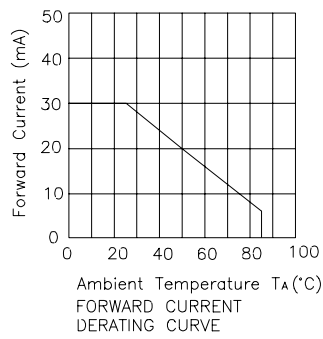
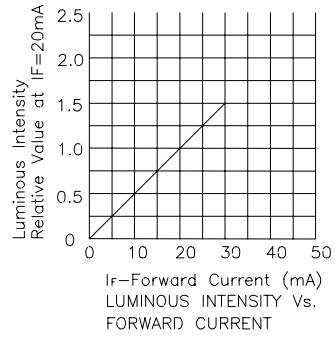
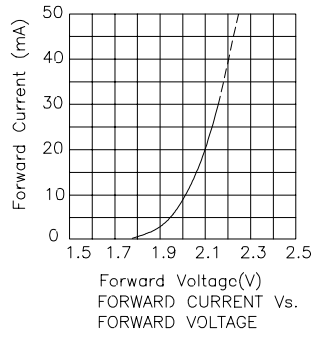
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
peak	Peak Wavelength	Blue	470		nm	I _F =20mA
D	Dominant Wavelength	Blue	470		nm	I _F =20mA
1/2	Spectral Line Half-width	Blue	25		nm	I _F =20mA
C	Capacitance	Blue	105		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Blue	3.3	4.0	V	I _F =20mA
I _R	Reverse Current	Blue		10	μA	V _R = 5V

Absolute Maximum Ratings at T_A=25 C

Parameter	Blue	Units
Power dissipation	105	mW
DC Forward Current	30	m A
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40 C To +85 C	

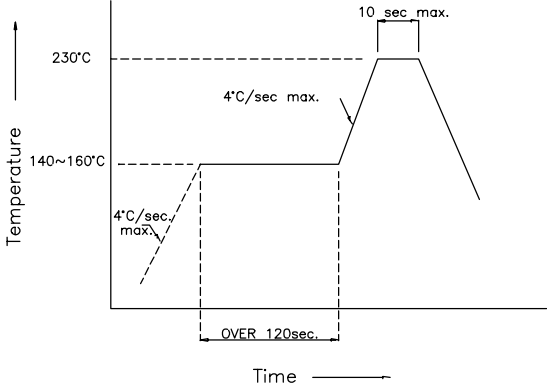
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

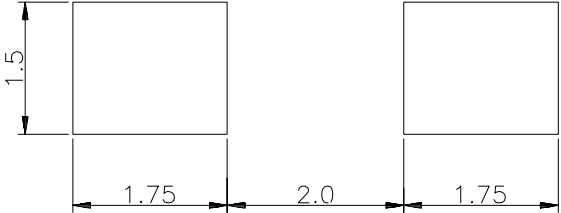


SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



**Recommended Soldering Pattern
(Units : mm)**



**Tape Specifications
(Units : mm)**

